



PATENT APPLICATION  
Docket No.: 9903-070  
Client No.: S02US037

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Hee-Jin Park, et al.      Conf. No.: 1321  
Serial No. 10/719,670      Examiner: Tho V. Duong  
Filed: November 20, 2003      Group Art Unit: 3743  
For: STACKED CHIP PACKAGE WITH HEAT TRANSFER  
WIRES

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO ELECTION REQUIREMENT**

Responsive to the Restriction Requirement, dated August 12, 2004, Applicant hereby elects Species represented by FIG 3., with traverse. Claims 1-2, 7-14, and 17-20 read on this species.

**Customer No. 20575**

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, PC

Hosoon Lee  
Limited Recognition Under 37 CFR § 10.9(b)

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450  
Date: September 1, 2004

  
Li Mei Vermilya